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### **AMENDMENTS TO THE SPECIFICATION**

Please replace paragraph [0037] with the following paragraph:

“As shown in FIG. 3A, during the electroplating process the front surface 12 of substrate 10 is brought into contact with the top surface 18 of the mask plate 16. As a plating solution, depicted by arrow 28, is delivered to the channel 22, the substrate 10 is rotated about a rotation axis 29 while the front surface 12 contacts the top surface 18 of the mask plate 16. For the purpose of clarification, the rotation axis 29 may be the point at which the closed end 24 of the channel 22, thereby ensuring that rotation of the substrate 10 will result in the entire front surface 12 of the substrate 10 having uniform contact with the channel 22. As the solution is delivered and fills the channel 22, it wets the front surface 12 of the substrate 10. As will be described in detail below, under an applied potential between the substrate and an anode, in the presence of the solution 28 that fills the channel 22, the metal, such as copper, is plated on the front surface 12 of the substrate and the front surface 12 of the substrate is also swept by the top surface ~~[[8]]~~ 18 of the plate 16. This sweeping of the top surface 18 of the plate 16 assists in obtaining planar deposition of the metal. The solution 28, which is continuously delivered under pressure, will then flow through the channel 22 in the direction of the arrow 30, towards the open end 26, and exits the plate 16.”